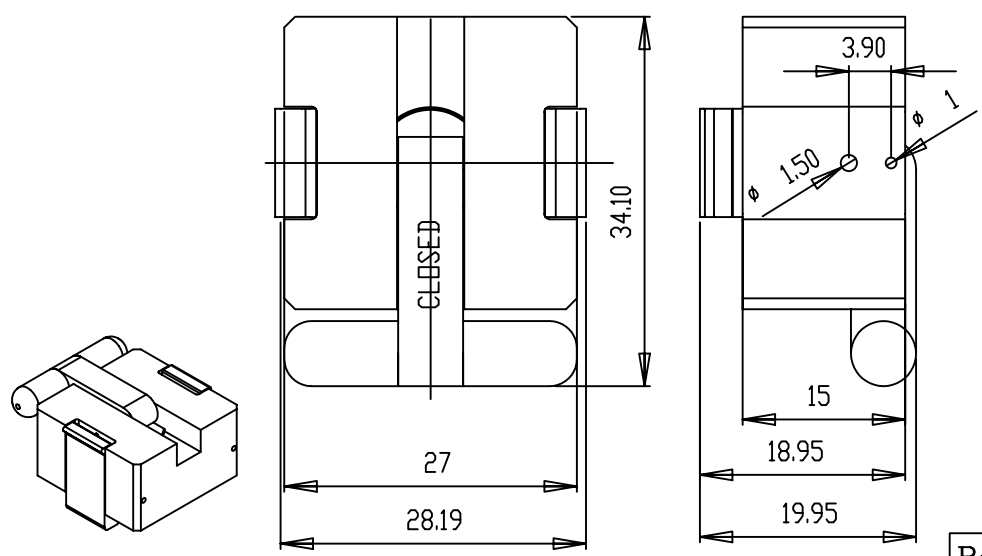


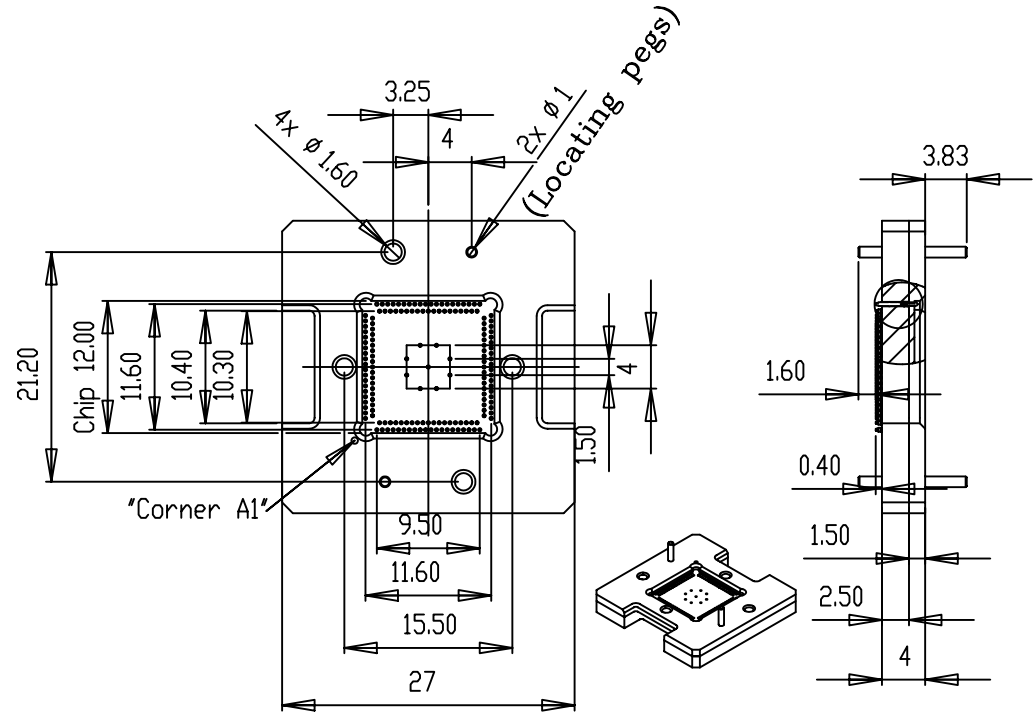
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	05/26/05	H.N.

SKT2311



RETENTION FRAME
 Material: Epoxy FR4
 Thickness: 15.00 mm

Recommended PCB layout
 for BGA Socket
 PCB holes for locating pegs
 - $\phi 1.10 \pm 0.02$
 PCB pad diameter
 minimum $\phi 0.30$



SOCKET
 Material: TG 200
 Thickness: 4.00 mm

RECOMMENDED PAD LAYOUT

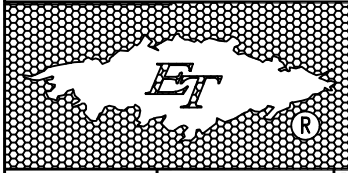
<p>SOLDERTAIL STYLE</p> <p>REGULAR SMT STYLE XX = (-SM) YY = (-30)</p> <p>RAISED SMT STYLE XX = (-SR) YY = (-29)</p>		<p>SOLDERTAIL = THRU HOLE STYLE</p> <p>XX = (-ET) YY = (-70)</p>	
<p>Pitch(PCB) *</p> <p>$\phi 0.118$ [$\phi 0.30\text{mm}$]</p> <p>PCB Layout</p>		<p>Pitch(PCB) *</p> <p>$\phi 0.138$ [$\phi 0.35\text{mm}$]</p> <p>PCB Layout</p>	
<p>BALL DIAMETER FOR:</p> <p>-30(SM) = .0098 [0.25mm] TO .0138 [0.35mm] -29(SR) = .0098 [0.25mm] TO .0138 [0.35mm]</p>		<p>PIN DIAMETER FOR:</p> <p>-70(ET) = .0098 [0.25mm]</p>	
<p>BALL HEIGHT FOR:</p> <p>-30(SM) = .0059 [0.15mm] TO .0118 [0.30mm] -29(SR) = .0059 [0.15mm] TO .0118 [0.30mm]</p>			

* All Dimensions Are Nominal For A .0197 [0.50mm] Pitch BGA Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 165
LEAD PITCH	= 0.50mm
GRID SIZE	= 20X20
PACKAGE SIZE	= 12.00mm

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED



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SHEET: 1 OF 1	DATE: 05/26/05	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: S-MLQ-00-165-XX	
Scale N/A DO NOT SCALE DRAWING			DESCRIPTION: MLQ-0165-ML56-YY